

型号: MT18Ex

- MicroThin™为带有18 μm载体箔的超薄铜箔。
MicroThin™ is ultra thin foil with 18 μm carrier foil.
- 适用于线宽/线距(L/S) =20/20 - 35/35的应用。
Usable for fine pitch pattern L/S=20/20 - 35/35 formation.
- 与MT18SD-H相比(Rz=3um), MT18Ex有更低的粗糙度(Rz=2um)适用于高精细线路。
Compared to MT18SD-H(Rz=3um), MT18Ex has smaller roughness(Rz=2um) and is more suitable for very fine patterning.

用途/Application

- 半导体封装基板
/Semiconductor Package
- 高密度多层基板
/High Density Interconnect

构成/Composition



生产地点/Production Site

- 日本 / Japan
- 马来西亚/Malaysia

代表性特性数据/Representative data

Model No.	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18Ex	2	24	2	-	-	1.2
	3	33	2	-	-	1.2
	5	51	2	-	-	1.2

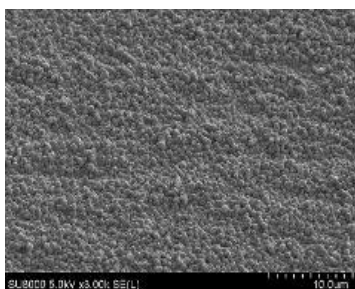
※上述列表为代表性数据, 非保证数据。

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm厚度之后的测试值

Evaluated after plated up to 35 μm.

处理面/Laminate side



阻剂面/Resist side

